

Data Sheet January 25, 2008 FN7311.8

#### 250MHz Differential Line Receivers

The EL5172 and EL5372 are single and triple high bandwidth amplifiers designed to extract the difference signal from noisy environments. They are primarily targeted for applications such as receiving signals from twisted-pair lines or any application where common mode noise injection is likely to occur.

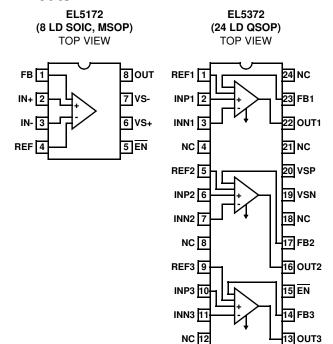
The EL5172 and EL5372 are stable for a gain of one and requires two external resistors to set the voltage gain.

The output common mode level is set by the reference pin  $(V_{REF})$ , which has a -3dB bandwidth of over 120MHz. Generally, this pin is grounded but it can be tied to any voltage reference.

The output can deliver a maximum of ±60mA and is short circuit protected to withstand a temporary overload condition.

The EL5172 is available in the 8 Ld SOIC and 8 Ld MSOP packages and the EL5372 in a 24 Ld QSOP package. Both are specified for operation over the full -40°C to +85°C temperature range.

## **Pinouts**



#### Features

- · Differential input range ±2.3V
- · 250MHz 3dB bandwidth
- 800V/µs slew rate
- · 60mA maximum output current
- Single 5V or dual ±5V supplies
- · Low power 5mA to 6mA per channel
- · Pb-free available (RoHS compliant)

## **Applications**

- · Twisted-pair receivers
- · Differential line receivers
- · VGA over twisted-pair
- · ADSL/HDSL receivers
- · Differential to single-ended amplification
- · Reception of analog signals in a noisy environment

# **Ordering Information**

PART NUMBER	PART MARKING	PACKAGE	PKG. DWG. #
EL5172IS	5172IS	8 Ld SOIC (150 mil)	MDP0027
EL5172IS-T7*	5172IS	8 Ld SOIC (150 mil)	MDP0027
EL5172IS-T13*	5172IS	8 Ld SOIC (150 mil)	MDP0027
EL5172ISZ (Note)	5172ISZ	8 Ld SOIC (150 mil) (Pb-free)	MDP0027
EL5172ISZ-T7* (Note)	5172ISZ	8 Ld SOIC (150 mil) (Pb-free)	MDP0027
EL5172ISZ-T13* (Note)	5172ISZ	8 Ld SOIC (150 mil) (Pb-free)	MDP0027
EL5172IY	h	8 Ld MSOP (3.0mm)	MDP0043
EL5172IY-T7*	h	8 Ld MSOP (3.0mm)	MDP0043
EL5172IY-T13*	h	8 Ld MSOP (3.0mm)	MDP0043
EL5172IYZ (Note)	BAAWA	8 Ld MSOP (3.0mm) (Pb-free)	MDP0043
EL5172IYZ-T7* (Note)	BAAWA	8 Ld MSOP (3.0mm) (Pb-free)	MDP0043
EL5172IYZ-T13* (Note)	BAAWA	8 Ld MSOP (3.0mm) (Pb-free)	MDP0043
EL5372IU	EL5372IU	24 Ld QSOP (150 mil)	MDP0040
EL5372IU-T7*	EL5372IU	24 Ld QSOP (150 mil)	MDP0040
EL5372IU-T13*	EL5372IU	24 Ld QSOP (150 mil)	MDP0040
EL5372IUZ (Note)	EL5372IUZ	24 Ld QSOP (150 mil) (Pb-free)	MDP0040
EL5372IUZ-T7* (Note)	EL5372IUZ	24 Ld QSOP (150 mil) (Pb-free)	MDP0040
EL5372IUZ-T13* (Note)	EL5372IUZ	24 Ld QSOP (150 mil) (Pb-free)	MDP0040

<sup>\*</sup>Please refer to TB347 for details on reel specifications.

NOTE: These Intersil Pb-free plastic packaged products employ special Pb-free material sets; molding compounds/die attach materials and 100% matte tin plate PLUS ANNEAL - e3 termination finish, which is RoHS compliant and compatible with both SnPb and Pb-free soldering operations. Intersil Pb-free products are MSL classified at Pb-free peak reflow temperatures that meet or exceed the Pb-free requirements of IPC/JEDEC J STD-020.

# EL5172, EL5372

# **Absolute Maximum Ratings** $(T_A = +25^{\circ}C)$

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#### **Thermal Information**

Operating Junction Temperature	С
Ambient Operating Temperature	С
Pb-free reflow profile see link below	w
http://www.intersil.com/pbfree/Pb-FreeReflow.asp	

CAUTION: Do not operate at or near the maximum ratings listed for extended periods of time. Exposure to such conditions may adversely impact product reliability and result in failures not covered by warranty.

IMPORTANT NOTE: All parameters having Min/Max specifications are guaranteed. Typ values are for information purposes only. Unless otherwise noted, all tests are at the specified temperature and are pulsed tests, therefore:  $T_J = T_C = T_A$ 

## **Electrical Specifications**

 $V_S$ + = +5V,  $V_S$ - = -5V,  $T_A$  = +25°C,  $V_{IN}$  = 0V,  $R_L$  = 500 $\Omega$ ,  $R_F$  = 0,  $R_G$  = OPEN,  $C_L$  = 2.7pF, Unless Otherwise Specified.

PARAMETER	DESCRIPTION	CONDITIONS	MIN	TYP	MAX	UNIT
AC PERFORMA	NCE					
BW	-3dB Bandwidth	A <sub>V</sub> =1, C <sub>L</sub> = 2.7pF		250		MHz
		$A_V = 2$ , $R_F = 1000\Omega$ , $C_L = 2.7pF$		70		MHz
		$A_V = 10, R_F = 1000\Omega, C_L = 2.7pF$		10		MHz
BW	±0.1dB Bandwidth	A <sub>V</sub> =1, C <sub>L</sub> = 2.7pF		25		MHz
SR	Slew Rate	$V_{OUT} = 3V_{P-P}$ , 20% to 80%, EL5172	550	800	1000	V/µs
		V <sub>OUT</sub> = 3V <sub>P-P</sub> , 20% to 80%, EL5372	550	700	1000	V/µs
t <sub>STL</sub>	Settling Time to 0.1%	V <sub>OUT</sub> = 2V <sub>P-P</sub>		10		ns
tovr	Output Overdrive Recovery Time			20		ns
GBWP	Gain Bandwidth Product			100		MHz
V <sub>REF</sub> BW (-3dB)	V <sub>REF</sub> -3dB Bandwidth	A <sub>V</sub> =1, C <sub>L</sub> = 2.7pF		120		MHz
V <sub>REF</sub> SR	V <sub>REF</sub> Slew Rate	V <sub>OUT</sub> = 2V <sub>P-P</sub> , 20% to 80%		600		V/µs
V <sub>N</sub>	Input Voltage Noise	at f = 11kHz		26		nV/√Hz
I <sub>N</sub>	Input Current Noise	at f = 11kHz		2		pA/√Hz
HD2	Second Harmonic Distortion	V <sub>OUT</sub> = 1V <sub>P-P</sub> , 5MHz		-66		dBc
		V <sub>OUT</sub> = 2V <sub>P-P</sub> , 50MHz		-63		dBc
HD3	Third Harmonic Distortion	V <sub>OUT</sub> = 1V <sub>P-P</sub> , 5MHz		-84		dBc
		V <sub>OUT</sub> = 2V <sub>P-P</sub> , 50MHz		-76		dBc
dG	Differential Gain at 3.58MHz	R <sub>L</sub> = 150Ω, A <sub>V</sub> = 2		0.04		%
dθ	Differential Phase at 3.58MHz	R <sub>L</sub> = 150Ω, A <sub>V</sub> = 2		0.41		0
e <sub>S</sub>	Channel Separation at 100kHz	EL5372 only		90		dB
INPUT CHARAC	TERISTICS					
V <sub>OS</sub>	Input Referred Offset Voltage			±7	±25	mV
I <sub>IN</sub>	Input Bias Current (V <sub>IN</sub> , V <sub>INB</sub> , V <sub>REF</sub> )		-14	-6	-3	μΑ
R <sub>IN</sub>	Differential Input Resistance			300		kΩ
C <sub>IN</sub>	Differential Input Capacitance			1		pF
DMIR	Differential Input Range		±2.1	±2.38	±2.5	V
CMIR+	Common Mode Positive Input Range at V <sub>IN</sub> +, V <sub>IN</sub> -		3.3	3.5		V
CMIR-	Common Mode Positive Input Range at V <sub>IN+</sub> , V <sub>IN-</sub>			-4.5	-4.3	
V <sub>REFIN+</sub>	Reference Input Positive Voltage Range	$V_{IN} + = V_{IN} - = 0V$	3.3	3.7		V
V <sub>REFIN-</sub>	Reference Input Negative Voltage Range	$V_{IN} + = V_{IN} - = 0V$		-3.9	-3.6	

# EL5172, EL5372

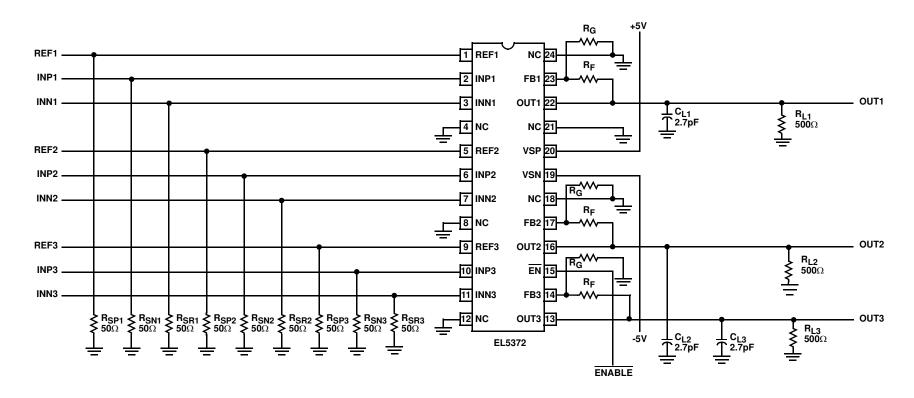
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PARAMETER	DESCRIPTION	CONDITIONS	MIN	TYP	MAX	UNIT
CMRR	Input Common Mode Rejection Ratio	V <sub>IN</sub> = ±2.5V	75	95		dB
Gain	Gain Accuracy	V <sub>IN</sub> = 1	0.985	1	1.015	V
OUTPUT CHAR	ACTERISTICS		II.			
V <sub>OUT</sub>	Positive Output Voltage Swing $R_L = 500\Omega$ to GND 3.3			3.63		V
	Negative Output Voltage Swing	$R_L = 500\Omega$ to GND		-3.87	-3.5	V
I <sub>OUT</sub> (Max)	Maximum Output Current	$R_L = 10\Omega$	±60	±95		mA
R <sub>OUT</sub>	Output Impedance			100		mΩ
SUPPLY			II.			
V <sub>SUPPLY</sub>	Supply Operating Range	V <sub>S</sub> + to V <sub>S</sub> -	4.75		11	V
I <sub>S (on)</sub>	Power Supply Current Per Channel - Enabled		4.6	5.6	7	mA
I <sub>S (off)</sub> +	Positive Power Supply Current - Disabled	EN pin tied to 4.8V, EL5172		80	100	μΑ
		EN pin tied to 4.8V, EL5372		1.7	5	μΑ
I <sub>S (off)</sub> -	Negative Power Supply Current - Disabled		-150	-120	-90	μΑ
PSRR	Power Supply Rejection Ratio	V <sub>S</sub> from ±4.5V to ±5.5V	50	58		dB
ENABLE	-1					
t <sub>EN</sub>	Enable Time			150		ns
t <sub>DS</sub>	Disable Time			1.4		μs
V <sub>IH</sub>	EN Pin Voltage for Power-up				V <sub>S</sub> + - 1.5	V
V <sub>IL</sub>	EN Pin Voltage for Shut-down		V <sub>S</sub> + - 0.5			V
I <sub>IH-EN</sub>	EN Pin Input Current High Per Channel	At V <sub>EN</sub> = 5V		40	60	μΑ
I <sub>IL-EN</sub>	EN Pin Input Current Low Per Channel	At V <sub>EN</sub> = 0V	-10	-3		μΑ

# EL5172, EL5372

# Pin Descriptions

EL5172	EL5372	PIN NAME	PIN FUNCTION
1		FB	Feedback input
2		IN+	Non-inverting input
3		IN-	Inverting input
4		REF	Sets the common mode output voltage level
5		EN	Enabled when this pin is floating or the applied voltage $\leq$ V <sub>S</sub> + - 1.5
6		VS+	Positive supply voltage
7		VS-	Negative supply voltage
8		OUT	Output voltage
	1, 5, 9	REF1, 2, 3	Reference input, controls common-mode output voltage
	2, 6, 10	INP1, 2, 3	Non-inverting inputs
	3, 7, 11	INN1, 2, 3	Inverting inputs
	4, 8, 12, 18, 21, 24	NC	No connect; grounded for best crosstalk performance
	13, 16, 22	OUT1, 2, 3	Non-inverting outputs
	14, 17, 23	FB1, 2, 3	Feedback from outputs
	15	EN	Enabled when this pin is floating or the applied voltage $\leq$ V <sub>S</sub> + - 1.5
	19	VSN	Negative supply
	20	VSP	Positive supply



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# **Typical Performance Curves**

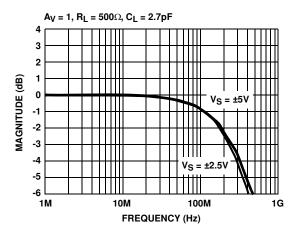


FIGURE 1. FREQUENCY RESPONSE vs SUPPLY VOLTAGE

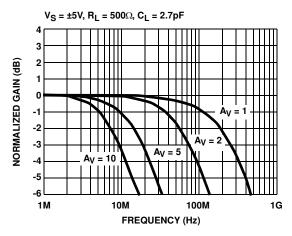


FIGURE 3. FREQUENCY RESPONSE vs VARIOUS GAIN

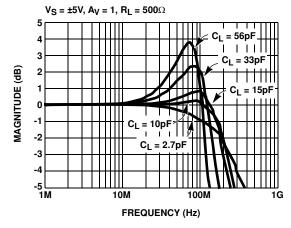


FIGURE 5. FREQUENCY RESPONSE vs CL

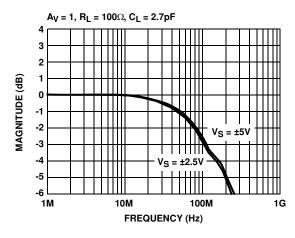


FIGURE 2. FREQUENCY RESPONSE vs SUPPLY VOLTAGE

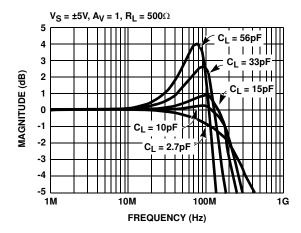


FIGURE 4. FREQUENCY RESPONSE vs CL

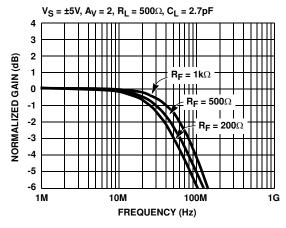


FIGURE 6. FREQUENCY RESPONSE FOR VARIOUS RF

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# Typical Performance Curves (Continued)

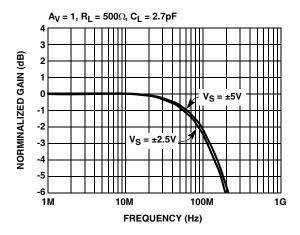


FIGURE 7. FREQUENCY RESPONSE FOR  $V_{REF}$ 

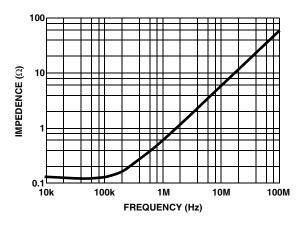


FIGURE 9. OUTPUT IMPEDANCE vs FREQUENCY

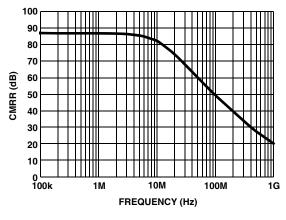


FIGURE 11. CMRR vs FREQUENCY

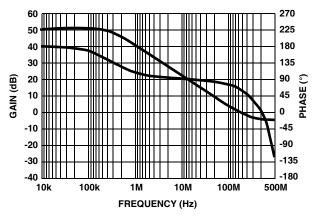


FIGURE 8. OPEN LOOP GAIN

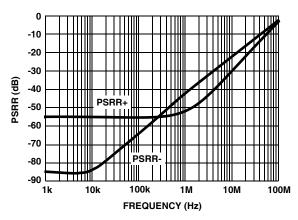


FIGURE 10. PSRR vs FREQUENCY

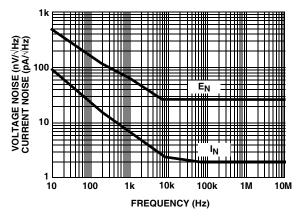


FIGURE 12. VOLTAGE AND CURRENT NOISE vs FREQUENCY

# Typical Performance Curves (Continued)

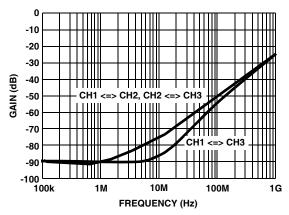
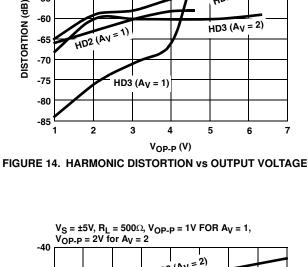


FIGURE 13. CHANNEL ISOLATION vs FREQUENCY



 $V_S = \pm 5V$ ,  $R_L = 500\Omega$ , f = 5MHz

HD2 (AV

-50

-55

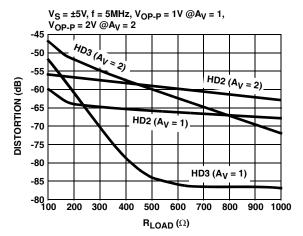


FIGURE 15. HARMONIC DISTORTION vs LOAD RESISTANCE

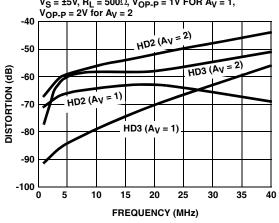


FIGURE 16. HARMONIC DISTORTION vs FREQUENCY

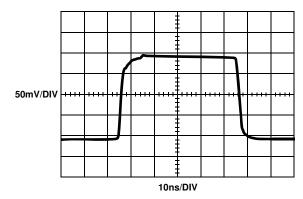


FIGURE 17. SMALL SIGNAL TRANSIENT RESPONSE

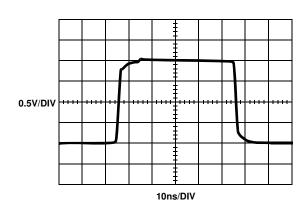
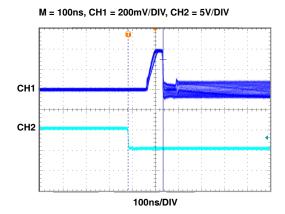


FIGURE 18. LARGE SIGNAL TRANSIENT RESPONSE

# Typical Performance Curves (Continued)



**FIGURE 19. ENABLED RESPONSE** 

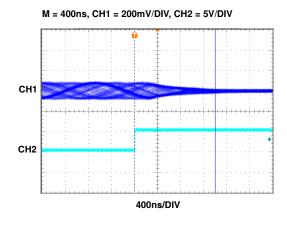


FIGURE 20. DISABLED RESPONSE

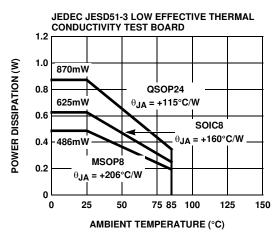


FIGURE 21. PACKAGE POWER DISSIPATION VS AMBIENT TEMPERATURE

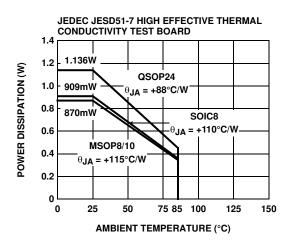
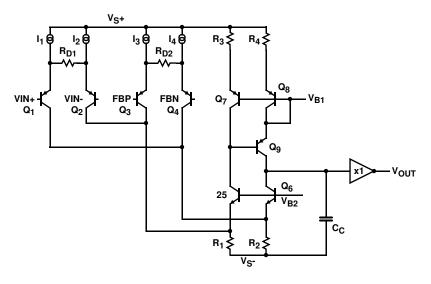


FIGURE 22. PACKAGE POWER DISSIPATION VS AMBIENT TEMPERATURE

# Simplified Schematic



# Description of Operation and Application Information

#### **Product Description**

The EL5172 and EL5372 are wide bandwidth, low power and single/differential ended to single ended output amplifiers. The EL5172 is a single channel differential to single ended amplifier. The EL5372 is a triple channel differential to single ended amplifier. The EL5172 and EL5372 are internally compensated for closed loop gain of +1 or greater. Connected in gain of 1 and driving a  $500\Omega$  load, the EL5172 and EL5372 have a -3dB bandwidth of 250MHz. Driving a  $150\Omega$  load at gain of 2, the bandwidth is about 50MHz. The bandwidth at the REF input is about 450MHz. The EL5172 and EL5372 are available with a power-down feature to reduce the power while the amplifier is disabled.

#### Input, Output and Supply Voltage Range

The EL5172 and EL5372 have been designed to operate with a single supply voltage of 5V to 10V or a split supplies with its total voltage from 5V to 10V. The amplifiers have an input common mode voltage range from -4.3V to 3.3V for ±5V supply. The differential mode input range (DMIR) between the two inputs is about from -2.3V to +2.3V. The input voltage range at the REF pin is from -3.6V to 3.3V. If the input common mode or differential mode signal is outside the above-specified ranges, it will cause the output signal to be distorted.

The output of the EL5172 and EL5372 can swing from -3.8V to 3.6V at  $500\Omega$  load at  $\pm 5V$  supply. As the load resistance becomes lower, the output swing is reduced respectively.

#### Over All Gain Settings

The gain setting for the EL5172 and the EL5372 is similar to the conventional operational amplifier. The output voltage is equal to the difference of the inputs plus  $V_{REF}$  and then times the gain.

$$V_{O} = (V_{IN} + -V_{IN} - +V_{REF}) \times \left(1 + \frac{R_{F}}{R_{G}}\right)$$

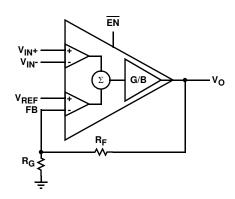


FIGURE 23.

#### Choice of Feedback Resistor and Gain Bandwidth Product

For applications that require a gain of +1, no feedback resistor is required. Just short the OUT pin to the FB pin. For gains greater than +1, the feedback resistor forms a pole with the parasitic capacitance at the inverting input. As this pole becomes smaller, the amplifier's phase margin is reduced. This causes ringing in the time domain and peaking in the frequency domain. Therefore,  $R_{\text{F}}$  has some maximum value that should not be exceeded for optimum performance. If a large value of  $R_{\text{F}}$  must be used, a small capacitor in the few Pico farad range in parallel with  $R_{\text{F}}$  can help to reduce the ringing and peaking at the expense of reducing the bandwidth.

The bandwidth of the EL5172 and EL5372 depends on the load and the feedback network.  $R_F$  and  $R_G$  appear in parallel with the load for gains other than +1. As this combination gets smaller, the bandwidth falls off. Consequently,  $R_F$  also has a minimum value that should not be exceeded for optimum bandwidth performance. For a gain of +1,  $R_F$  = 0 is optimum. For the gains other than +1, optimum response is obtained with  $R_F$  between  $500\Omega$  to  $1k\Omega$ . For  $A_V$  = 2 and  $R_F$  =  $R_G$  =  $1k\Omega$ , the BW is about 80 MHz and the frequency response is very flat.

The EL5172 and EL5372 have a gain bandwidth product of 100MHz. For gains ≥5, its bandwidth can be predicted by Equation 1:

$$Gain \times BW = 100MHz \tag{EQ. 1}$$

### **Driving Capacitive Loads and Cables**

The EL5172 and EL5372 can drive 56pF capacitance in parallel with  $500\Omega$  load to ground with 4dB of peaking at gain of +1. If less peaking is desired in applications, a small series resistor (usually between  $5\Omega$  to  $50\Omega$ ) can be placed in series with each output to eliminate most peaking. However, this will reduce the gain slightly. If the gain setting is greater than 1, the gain resistor  $R_G$  can then be chosen to make up for any gain loss which may be created by the additional series resistor at the output.

When used as a cable driver, double termination is always recommended for reflection-free performance. For those applications, a back-termination series resistor at the amplifier's output will isolate the amplifier from the cable and allow extensive capacitive drive. However, other applications may have high capacitive loads without a back-termination resistor. Again, a small series resistor at the output can help to reduce peaking.

#### Disable/Power-Down

The EL5172 and EL5372 can be disabled and its outputs placed in a high impedance state. The turn-off time is about 1.4 $\mu$ s and the turn-on time is about 150ns. When disabled, the amplifier's supply current is reduced to 80 $\mu$ A for IS+ and

120 $\mu$ A for I<sub>S</sub>- typically, thereby effectively eliminating the power consumption. The amplifier's power-down can be controlled by standard CMOS signal levels at the ENABLE pin. The applied logic signal is relative to V<sub>S</sub>+ pin. Letting the EN pin float or applying a signal that is less than 1.5V below V<sub>S</sub>+ will enable the amplifier. The amplifier will be disabled when the signal at EN pin is above V<sub>S</sub>+ - 0.5V. If a TTL signal is used to control the enabled/disabled function, Figure 24 could be used to convert the TTL signal to CMOS signal.

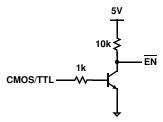


FIGURE 24.

#### **Output Drive Capability**

The EL5172 and EL5372 have internal short circuit protection. Its typical short circuit current is ±95mA. If the output is shorted indefinitely, the power dissipation could easily increase such that the part will be destroyed. Maximum reliability is maintained if the output current never exceeds ±60mA. This limit is set by the design of the internal metal interconnections.

#### **Power Dissipation**

With the high output drive capability of the EL5172 and EL5372, it is possible to exceed the +135°C absolute maximum junction temperature under certain load current conditions. Therefore, it is important to calculate the maximum junction temperature for the application to determine if the load conditions or package types need to be modified for the amplifier to remain in the safe operating area.

The maximum power dissipation allowed in a package is determined according to Equation 2:

$$PD_{MAX} = \frac{T_{JMAX} - T_{AMAX}}{\Theta_{JA}}$$
 (EQ. 2)

- T<sub>JMAX</sub> = Maximum junction temperature
- T<sub>AMAX</sub> = Maximum ambient temperature
- θ<sub>JA</sub> = Thermal resistance of the package

Assuming the REF pin is tied to GND for  $V_S = \pm 5V$  application, the maximum power dissipation actually produced by an IC is the total quiescent supply current times the total power supply voltage, plus the power in the IC due to the load, or:

For sourcing, use Equation 3:

$$PD_{MAX} = \left[V_{S} \times I_{SMAX} + (V_{S} + -V_{OUT}) \times \frac{V_{OUT}}{R_{LOAD}}\right] \times i$$
 (EQ. 3)

For sinking, use Equation 4:

$$PD_{MAX} = [V_S \times I_{SMAX} + (V_{OUT} - V_{S}^-) \times I_{LOAD}] \times i$$
 (EQ. 4)

#### Where:

- V<sub>S</sub> = Total supply voltage
- I<sub>SMAX</sub> = Maximum quiescent supply current per channel
- V<sub>OUT</sub> = Maximum output voltage of the application
- R<sub>LOAD</sub> = Load resistance
- I<sub>LOAD</sub> = Load current
- i = Number of channels

By setting the two  $PD_{MAX}$  equations equal to each other, we can solve the output current and  $R_{LOAD}$  to avoid the device overheat.

# Power Supply Bypassing and Printed Circuit Board Layout

As with any high frequency device, a good printed circuit board layout is necessary for optimum performance. Lead lengths should be as short as possible. The power supply pin must be well bypassed to reduce the risk of oscillation. For normal single supply operation, where the  $V_S$ - pin is connected to the ground plane, a single 4.7µF tantalum capacitor in parallel with a 0.1µF ceramic capacitor from  $V_S+$  to GND will suffice. This same capacitor combination should be placed at each supply pin to ground if split supplies are to be used. In this case, the  $V_S$ - pin becomes the negative supply rail.

For good AC performance, parasitic capacitance should be kept to a minimum. Use of wire wound resistors should be avoided because of their additional series inductance. Use of sockets should also be avoided if possible. Sockets add parasitic inductance and capacitance that can result in compromised performance. Minimizing parasitic capacitance at the amplifier's inverting input pin is very important. The feedback resistor should be placed very close to the inverting input pin. Strip line design techniques are recommended for the signal traces.

## Typical Applications

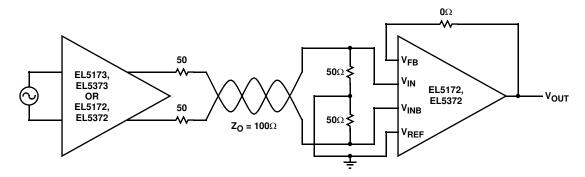


FIGURE 25. TWISTED PAIR CABLE RECEIVER

As the signal is transmitted through a cable, the high frequency signal will be attenuated. One way to compensate for this loss is to boost the high frequency gain at the receiver side.

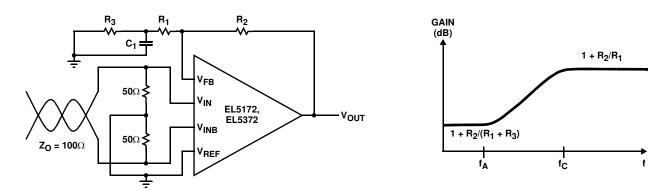


FIGURE 26. COMPENSATED LINE RECEIVER

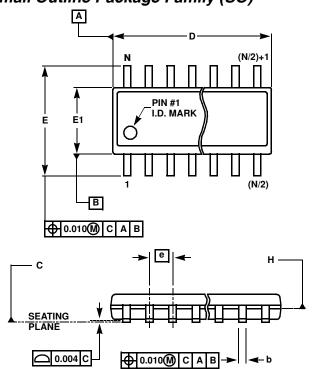
#### Level Shifter and Signal Summer

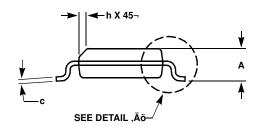
The EL5172 and EL5372 contains two pairs of differential pair input stages, which make sure that the inputs are all high impedance inputs. To take advantage of the two high impedance inputs, the EL5172 and EL5372 can be used as a signal summer to add two signals together. One signal can be applied to VIN+, the second signal can be applied to REF and  $V_{\text{IN}^-}$  is ground. The output is equal to Equation 5:

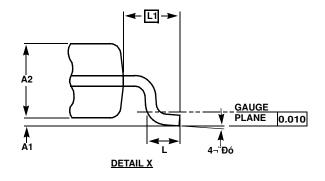
$$V_O = (V_{IN} + + V_{REF}) \times Gain$$
 (EQ. 5)

Also, the EL5172 and EL5372 can be used as a level shifter by applying a level control signal to the REF input.

# Small Outline Package Family (SO)







# **MDP0027**

#### **SMALL OUTLINE PACKAGE FAMILY (SO)**

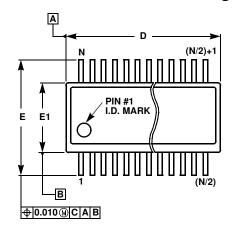
	INCHES								
SYMBOL	SO-8	SO-14	SO16 (0.150")	SO16 (0.300") (SOL-16)	SO20 (SOL-20)	SO24 (SOL-24)	SO28 (SOL-28)	TOLERANCE	NOTES
Α	0.068	0.068	0.068	0.104	0.104	0.104	0.104	MAX	-
A1	0.006	0.006	0.006	0.007	0.007	0.007	0.007	±0.003	-
A2	0.057	0.057	0.057	0.092	0.092	0.092	0.092	±0.002	-
b	0.017	0.017	0.017	0.017	0.017	0.017	0.017	±0.003	-
С	0.009	0.009	0.009	0.011	0.011	0.011	0.011	±0.001	-
D	0.193	0.341	0.390	0.406	0.504	0.606	0.704	±0.004	1, 3
Е	0.236	0.236	0.236	0.406	0.406	0.406	0.406	±0.008	-
E1	0.154	0.154	0.154	0.295	0.295	0.295	0.295	±0.004	2, 3
е	0.050	0.050	0.050	0.050	0.050	0.050	0.050	Basic	-
L	0.025	0.025	0.025	0.030	0.030	0.030	0.030	±0.009	-
L1	0.041	0.041	0.041	0.056	0.056	0.056	0.056	Basic	-
h	0.013	0.013	0.013	0.020	0.020	0.020	0.020	Reference	-
N	8	14	16	16	20	24	28	Reference	-

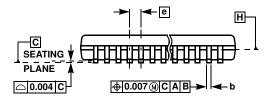
NOTES:

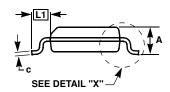
Rev. M 2/07

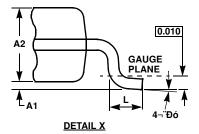
- 1. Plastic or metal protrusions of 0.006" maximum per side are not included.
- 2. Plastic interlead protrusions of 0.010" maximum per side are not included.
- 3. Dimensions "D" and "E1" are measured at Datum Plane "H".
- 4. Dimensioning and tolerancing per ASME Y14.5M-1994

# Quarter Size Outline Plastic Packages Family (QSOP)









#### MDP0040

## QUARTER SIZE OUTLINE PLASTIC PACKAGES FAMILY

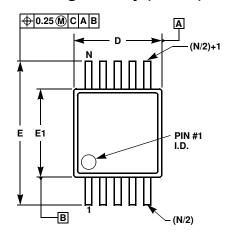
	INCHES				
SYMBOL	QSOP16	QSOP24	QSOP28	TOLERANCE	NOTES
Α	0.068	0.068	0.068	Max.	-
A1	0.006	0.006	0.006	±0.002	-
A2	0.056	0.056	0.056	±0.004	-
b	0.010	0.010	0.010	±0.002	-
С	0.008	0.008	0.008	±0.001	-
D	0.193	0.341	0.390	±0.004	1, 3
E	0.236	0.236	0.236	±0.008	-
E1	0.154	0.154	0.154	±0.004	2, 3
е	0.025	0.025	0.025	Basic	-
L	0.025	0.025	0.025	±0.009	-
L1	0.041	0.041	0.041	Basic	-
N	16	24	28	Reference	-

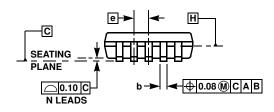
Rev. F 2/07

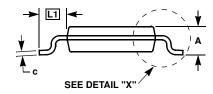
#### NOTES:

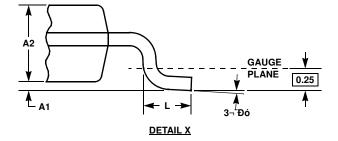
- Plastic or metal protrusions of 0.006" maximum per side are not included.
- 2. Plastic interlead protrusions of 0.010" maximum per side are not included.
- 3. Dimensions "D" and "E1" are measured at Datum Plane "H".
- 4. Dimensioning and tolerancing per ASME Y14.5M-1994.

# Mini SO Package Family (MSOP)









## MDP0043 MINI SO PACKAGE FAMILY

	MILLIMETERS			
SYMBOL	MSOP8	MSOP10	TOLERANCE	NOTES
Α	1.10	1.10	Max.	-
A1	0.10	0.10	±0.05	-
A2	0.86	0.86	±0.09	-
b	0.33	0.23	+0.07/-0.08	-
С	0.18	0.18	±0.05	-
D	3.00	3.00	±0.10	1, 3
E	4.90	4.90	±0.15	-
E1	3.00	3.00	±0.10	2, 3
е	0.65	0.50	Basic	-
L	0.55	0.55	±0.15	-
L1	0.95	0.95	Basic	-
N	8	10	Reference	-

Rev. D 2/07

#### NOTES:

- Plastic or metal protrusions of 0.15mm maximum per side are not included.
- Plastic interlead protrusions of 0.25mm maximum per side are not included.
- 3. Dimensions "D" and "E1" are measured at Datum Plane "H".
- 4. Dimensioning and tolerancing per ASME Y14.5M-1994.

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